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|-----------------------------------|---------------------------------------|--|-------------|
| <b>Notice of References Cited</b> | Application/Control No.<br>10/697,898 | Applicant(s)/Patent Under<br>Reexamination<br>KAUTZ ET AL. |             |
|                                   | Examiner<br>Christian Wilson          | Art Unit<br>2824   | Page 1 of 1 |

#### U.S. PATENT DOCUMENTS

| * |   | Document Number<br>Country Code-Number-Kind Code | Date<br>MM-YYYY | Name           | Classification |
|---|---|--|-----------------|----------------|----------------|
|   | A | US-6,377,464                                     | 04-2002         | Hashemi et al. | 361/760        |
|   | B | US-6,642,064                                     | 11-2003         | Terrill et al. | 438/15         |
|   | C | US-6,677,668                                     | 01-2004         | Lin, Paul T.   | 257/685        |
|   | D | US-6,700,196                                     | 03-2004         | Kautz et al.   | 257/723        |
|   | E | US-6,707,141                                     | 03-2004         | Akram, Salman  | 257/686        |
|   | F | US-  |                 |                |                |
|   | G | US-  |                 |                |                |
|   | H | US-  |                 |                |                |
|   | I | US-  |                 |                |                |
|   | J | US-  |                 |                |                |
|   | K | US-  |                 |                |                |
|   | L | US-  |                 |                |                |
|   | M | US-  |                 |                |                |

#### FOREIGN PATENT DOCUMENTS

| * |   | Document Number<br>Country Code-Number-Kind Code | Date<br>MM-YYYY | Country | Name | Classification |
|---|---|--|-----------------|---------|------|----------------|
|   | N |  |                 |         |      |                |
|   | O |  |                 |         |      |                |
|   | P |  |                 |         |      |                |
|   | Q |  |                 |         |      |                |
|   | R |  |                 |         |      |                |
|   | S |  |                 |         |      |                |
|   | T |  |                 |         |      |                |

#### NON-PATENT DOCUMENTS

| * |   | Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)   |
|---|---|---|
|   | U | Cotton <i>et al.</i> , Design and Development Challenges for Complex Laminate Multichip Modules, <i>International Conf. Multichip Modules</i> , (Apr 1997) 196. |
|   | V |   |
|   | W |   |
|   | X |   |

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.